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PATENT
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Takahiro Iijima, et al.
Serial No.: 10/693,374
Filed: October 24, 2003
For: SEMICONDUCTOR PACKAGE
AND METHOD OF PRODUCTION
THEREOF
Art Unit: 2823
Examiner:
Atty. Doc: 188-03

CERTIFICATE OF MAILING
DATE OF DEPOSIT September 7, 2005

I hereby certify that this correspondence is being deposited with the United States Post Office as first class mail, under 37 CFR §1.8, postage prepaid in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date shown above.

Name of person mailing paper or fee:
John J. Simkanich

SIGNATURE:

COVER LETTER WITH CERTIFICATE OF MAILING

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Enclosed and attached hereto are the following:

- 1) Cover Letter with Certificate of Mailing;
- 2) Amendment (9 pages); and
- 3) Postcard to be date-stamped and returned.

No fees are believed to be required. In the event that a fee is required with respect to this communication, the Commissioner is hereby authorized to charge any such fees, or credit any overpayment, to Paul & Paul Deposit Account No.16-0750.

Respectfully Submitted,

Date: September 7, 2005

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AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to a non-final Office Action dated June 23, 2005, to which a response is due by September 23, 2005, kindly amend the above-identified patent application as follows.

In the claims:

Amend the claims as follows.

1.(cancelled)

2.(cancelled)

3.(currently amended) A method of production of a semiconductor package having mounting a capacitor for suppressing fluctuations of a power-supply voltage provided to a semiconductor device mounted to a board, comprising:

providing a grounded interconnect pattern on an inside layer of said board.